

Single N-Channel 1.5 V Specified PowerTrench® MOSFET

20 V, 9.4 A, 14.5 mΩ

May 2012

Features

- Max $r_{DS(on)}$ = 14.5 mΩ at $V_{GS} = 4.5$ V, $I_D = 9.4$ A
- Max $r_{DS(on)}$ = 18.2 mΩ at $V_{GS} = 2.5$ V, $I_D = 8.3$ A
- Max $r_{DS(on)}$ = 23.3 mΩ at $V_{GS} = 1.8$ V, $I_D = 7.3$ A
- Max $r_{DS(on)}$ = 32.3 mΩ at $V_{GS} = 1.5$ V, $I_D = 6.2$ A
- Low Profile-0.8 mm maximum in the new package MicroFET 2x2 mm
- RoHS Compliant

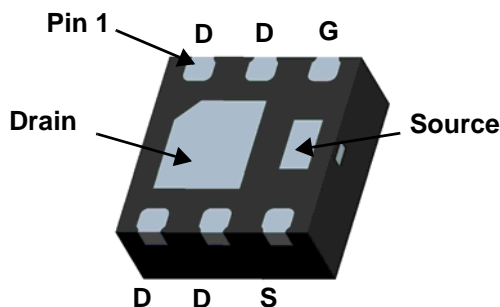


General Description

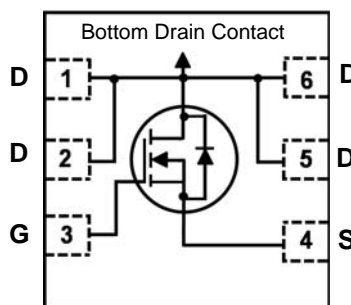
This Single N-Channel MOSFET has been designed using Fairchild Semiconductor's advanced Power Trench® process to optimize the $r_{DS(ON)}$ @ $V_{GS} = 1.5$ V on special MicroFET leadframe.

Applications

- Li-Ion Battery Pack
- DC-DC Buck Converters



MicroFET 2X2 (Bottom View)



MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	20	V
V_{GS}	Gate to Source Voltage	±8	V
I_D	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	9.4	A
	-Pulsed	54	
P_D	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	1.9	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1b)	0.7	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	65	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1b)	180	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
104	FDMA7628	MicroFET 2X2	7"	12 mm	3000 units

Electrical Characteristics $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0\text{ V}$	20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, referenced to $25\text{ }^{\circ}\text{C}$		15		mV/ $^{\circ}\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 16\text{ V}$, $V_{GS} = 0\text{ V}$			1	μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 8\text{ V}$, $V_{DS} = 0\text{ V}$			± 100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\text{ }\mu\text{A}$	0.4	0.6	1.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, referenced to $25\text{ }^{\circ}\text{C}$		-3		mV/ $^{\circ}\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 4.5\text{ V}$, $I_D = 9.4\text{ A}$		11.3	14.5	m Ω
		$V_{GS} = 2.5\text{ V}$, $I_D = 8.3\text{ A}$		12.7	18.2	
		$V_{GS} = 1.8\text{ V}$, $I_D = 7.3\text{ A}$		15.0	23.3	
		$V_{GS} = 1.5\text{ V}$, $I_D = 6.2\text{ A}$		18.3	32.3	
		$V_{GS} = 4.5\text{ V}$, $I_D = 9.4\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$		14.7	18.3	
g_{FS}	Forward Transconductance	$V_{DD} = 5\text{ V}$, $I_D = 9.4\text{ A}$		56		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 10\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$		1260	1680	pF
C_{oss}	Output Capacitance			180	240	pF
C_{rss}	Reverse Transfer Capacitance			122	185	pF
R_g	Gate Resistance			1.9		Ω

Switching Characteristics

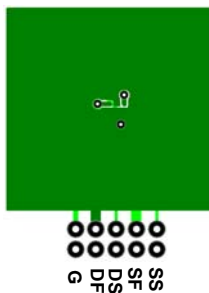
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 10\text{ V}$, $I_D = 9.4\text{ A}$, $V_{GS} = 4.5\text{ V}$, $R_{GEN} = 6\text{ }\Omega$		9	17	ns
t_r	Rise Time			6	11	ns
$t_{d(off)}$	Turn-Off Delay Time			37	58	ns
t_f	Fall Time			6	11	ns
Q_g	Total Gate Charge	$V_{GS} = 0\text{ V to } 4.5\text{ V}$	$V_{DD} = 10\text{ V}$, $I_D = 9.4\text{ A}$	17.5		nC
	Total Gate Charge	$V_{GS} = 0\text{ V to } 2.5\text{ V}$		10.0		nC
	Total Gate Charge	$V_{GS} = 0\text{ V to } 1.8\text{ V}$		7.4		nC
	Total Gate Charge	$V_{GS} = 0\text{ V to } 1.5\text{ V}$		6.2		nC
Q_{gs}	Gate to Source Charge			1.7		nC
Q_{gd}	Gate to Drain "Miller" Charge			2.7		nC

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain-Source Diode Forward Current				2.0	A
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 2.0 A (Note 2) I _F = 9.4 A, di/dt = 100 A/μs		0.63	1.2	V
t _{rr}	Reverse Recovery Time			16	29	ns
Q _{rr}	Reverse Recovery Charge			5	10	nC

NOTES:

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



a. 65 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 180 °C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

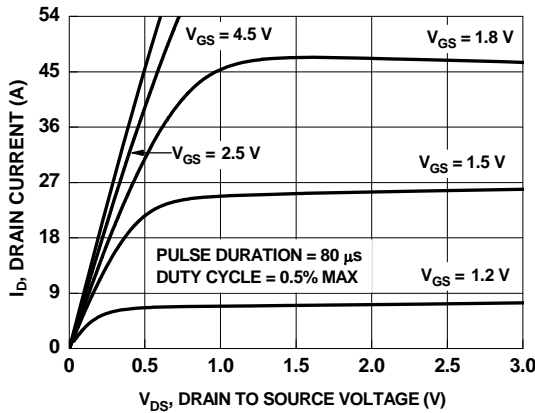


Figure 1. On Region Characteristics

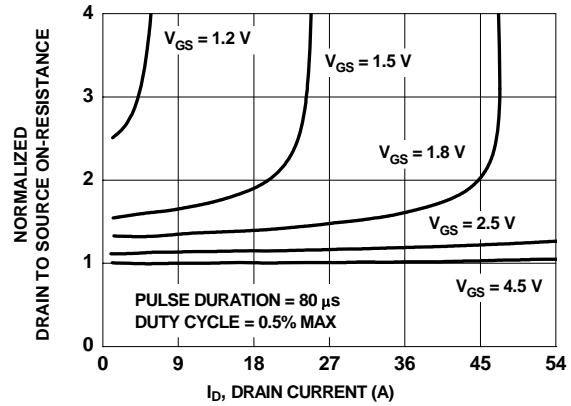


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

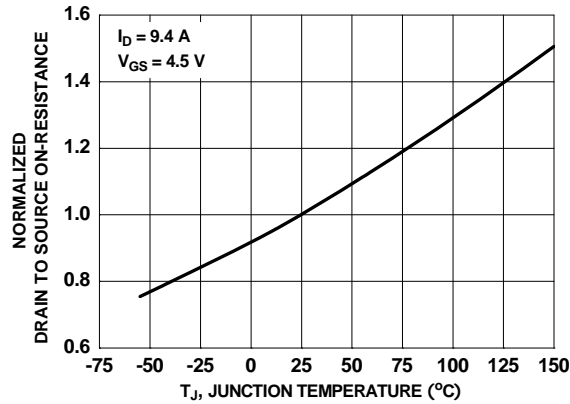


Figure 3. Normalized On Resistance vs Junction Temperature

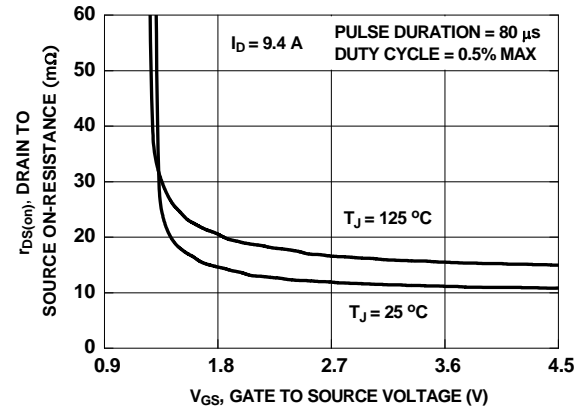


Figure 4. On-Resistance vs Gate to Source Voltage

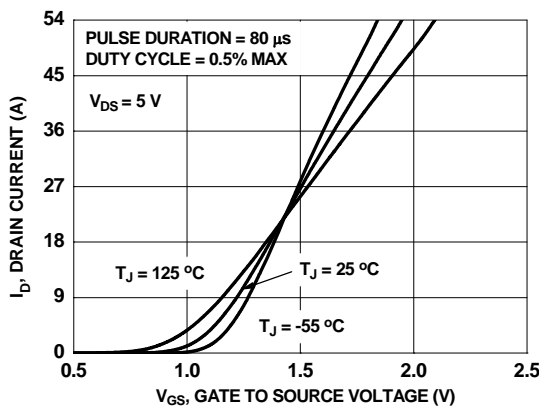


Figure 5. Transfer Characteristics

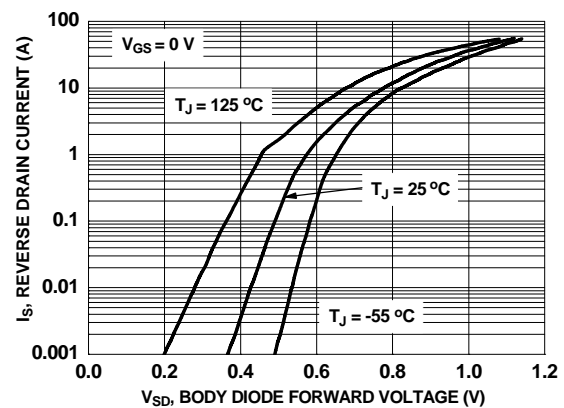


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

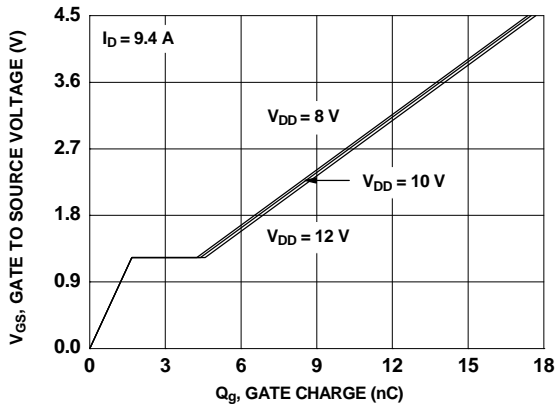


Figure 7. Gate Charge Characteristics

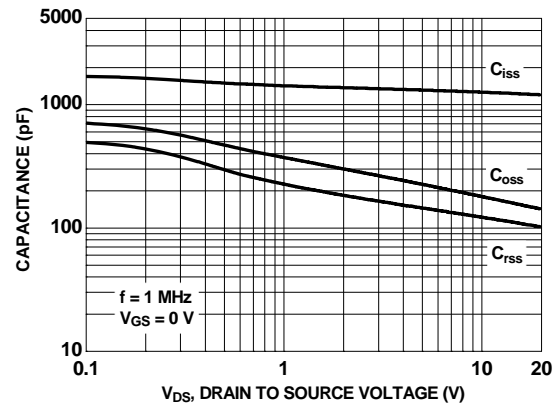


Figure 8. Capacitance vs Drain to Source Voltage

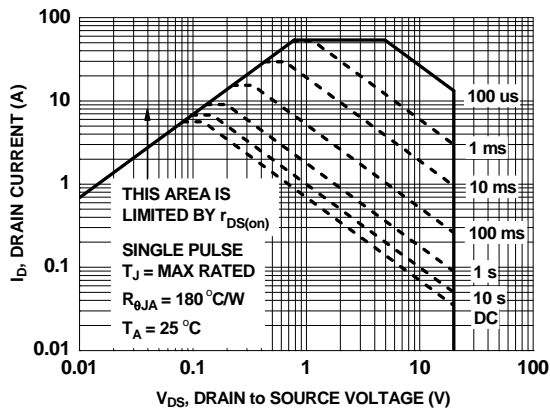


Figure 9. Forward Bias Safe Operating Area

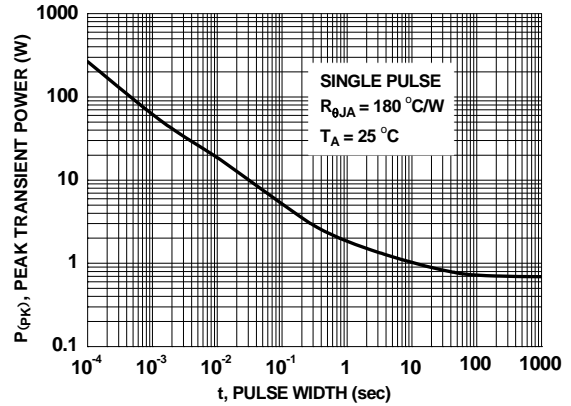


Figure 10. Single Pulse Maximum Power Dissipation

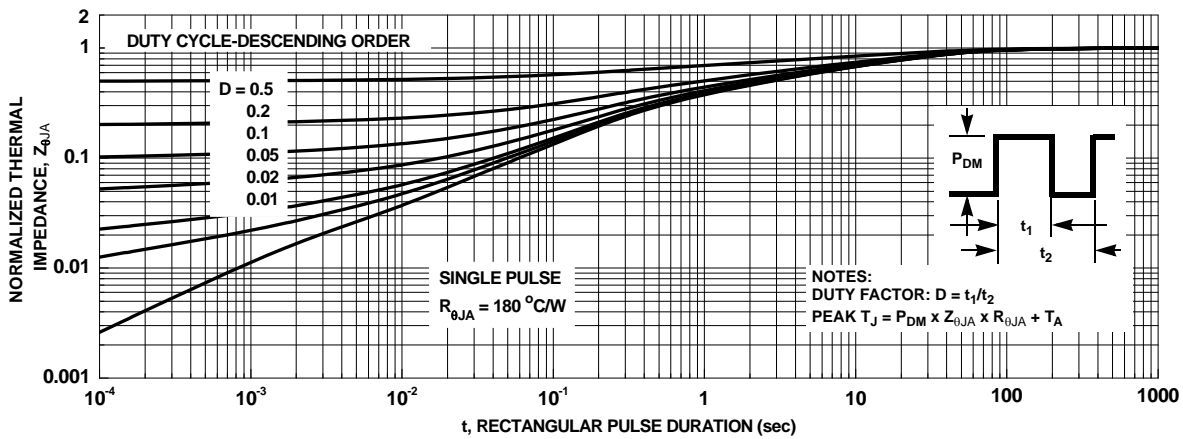
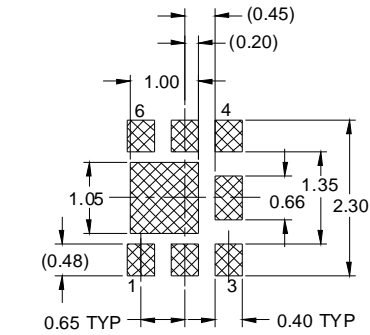
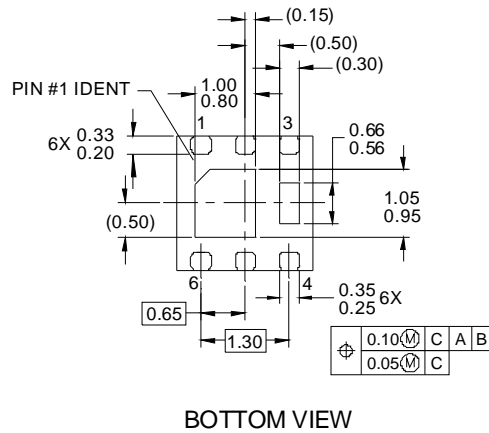
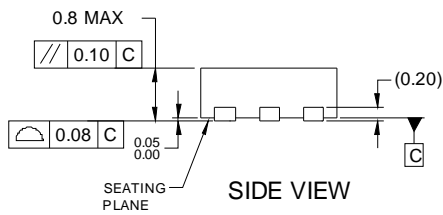
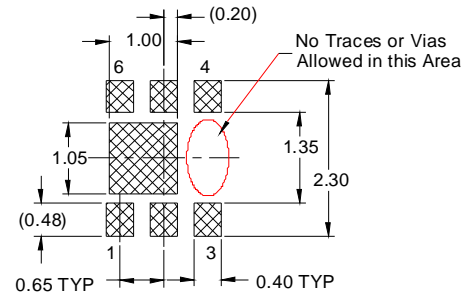
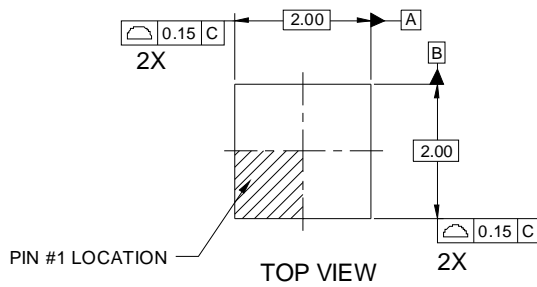


Figure 11. Junction-to-Ambient Transient Thermal Response Curve

Dimensional Outline and Pad Layout








NOTES:

- A. DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-229 DATED AUG/2003
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994



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